# Dow ENDURANCE™ HFDA-0801 BK EHV

# Supersmooth, Extra-Clean, Crosslinkable Semiconductive Shielding Compound

## The Dow Chemical Company

### Message:

DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV is a specially formulated semiconductive, vulcanizable compound designed for conductor shield and bonded insulation shield applications in high and extra-high voltage crosslinked polyethylene insulated cables.(1) DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV has demonstrated compatibility with copper and aluminum conductors.

DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV was specifically developed utilizing a special acetylene carbon black to provide a supersmooth surface to achieve best in class performance and yielding a more perfect interface between the extruded shield and the insulation. As a result, significantly improved cable performance can be expected.

#### Specifications

DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV is designed for use in power distribution cables. Cables with conductor and insulation shielding of DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV, prepared using sound commercial fabrication practice, would be expected to meet the following specifications: AEIC: CS8, CS9

IEC: 60502, 60840, 62067 ICEA: S-108-720; S-94-649; S-97-682, S-93-639 DIN: VDE 0276-632, 0276-620 BS: 6622 CENELEC: HD620 S1, HD632 S1 ISO 1872-E/BA, KHXY, 23-G200, C40 NF: C33-223, C33-226 UTE: C33-223

(1) DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV is recommended for use in conjunction with DOW cross-linked polyethylene and tree-retardant cross-linked polyethylene compounds. For other polymer insulation such as EPR and EPDM's, the user is cautioned to establish the utility of DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV with each formulation.

General Information				
Uses	Extra High Voltage Semiconductive Shield			
	Semiconductive Shield			
	Underground cable			
	Cable guard			
	Wire and cable applications			
Agency Ratings	AEIC CS8			
	AEIC CS9			
	BS 6622			
	DIN VDE 0276-620			
	DIN VDE 0276-632			
	ICEA S-93-639			
	ICEA S-94-649			
	ICEA S-97-682			
	IEC 60502			
	IEC 60840			
	IEC 62067			
	ISO 1872 E/BA KHXY 23G200 C40			
	NF C 33-223			
	NF C 33-226			

Black		
Particle		
Nominal Value	Unit	Test Method
1.14	g/cm³	ASTM D792
> 504	hr	ASTM D1693
Nominal Value	Unit	Test Method
14.5	MPa	ASTM D638
200	%	ASTM D638
Nominal Value	Unit	Test Method
98	%	ASTM D638
90	%	ASTM D638
Nominal Value	Unit	Test Method
-40.0	°C	ASTM D746
Nominal Value	Unit	Test Method
		ASTM D991
15	ohms•cm	ASTM D991
60	ohms∙cm	ASTM D991
		ASTM D991
	Particle   Nominal Value   1.14   > 504   Nominal Value   14.5   200   Nominal Value   98   90   Nominal Value   -40.0   Nominal Value   15	ParticleNominal ValueUnit1.14g/cm³> 504hrNominal ValueUnit14.5MPa200%Nominal ValueUnit98%90%Nominal ValueUnit-40.0°CNominal ValueUnit15ohms·cm

#### Additional Information

Nominal property values above represent tests on molded stress-relieved slabs. Cure times were 15 minutes at 175°C.Extra-Clean Requirements Among many desirable characteristics, DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV is extra-clean. DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV typically has less than 0.005% sulfur and less than 0.01% ash. The raw materials used for DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV are cleaner by design than those used for conventional semiconductive materials. Additional precautions are employed during the manufacture of DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV relative to conventional conductor shields to prevent introduction of any contamination to the raw materials and to the final product. These low levels of contamination can be expected to play a positive role in the manufacture of a totally extra-clean cable.

#### Supersmooth Extruded Surface

DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV meets the strictest standards of smoothness established for a crosslinkable semiconductive shield compound. The extruded surface of DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV must meet a smoothness specification that is more rigorous that typical supersmooth semiconductive shields. Throughout the production process, the product is tested to ensure smoothness. Extruded tapes are scanned by an automatic inspection system in a clean room. The tape smoothness data is managed using an acceptance sampling plan, which ensures that the shipping container meets or exceeds the product's smoothness standard. The DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV smoothness standard has been designed to meet the global industry specifications for semiconductive shield materials on high voltage and extra high voltage cables. Each batch of DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV meets the following smoothness requirement:

Protrusion Height / Maximum Allowable

50-59 µm / 0 per m<sup>2</sup>

60-74 µm / 0 per m<sup>2</sup>

>75 µm / 0 per m<sup>2</sup>

Storage

The environment or conditions of storage greatly influences the recommended storage time. Storage should be in accordance with good manufacturing practices. If proper warehousing and storage temperatures [dry conditions, between 50°F and 86°F (10°C and 30°C) in temperature] are utilized, this product may be stored by the customer for up to one year. It is recommended that the practice of using the product on a first-in / first-out basis be established. Storage under extreme conditions may affect the quality, processing, or performance of the product.

Extrusion	Nominal Value	Unit
Drying Temperature	60.0 - 70.0	°C
Drying Time	< 6.0	hr
Melt Temperature	121 - 140	°C
Extrusion instructions		

DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV provides excellent surface finish and outstanding output rates over a broad range of conditions. For optimum results, use melt extrusion temperatures in the suggested range of 250 to 285°F (121 to 140°C) to avoid pre-cure or scorch. Extruder barrel settings of 110°C (230°F) are suggested as a starting point while learning to process DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV. Specific machine settings will depend on the extruder design and must be established through conventional practices.Dehumidified air hopper drying at 140-160°F (60-70°C) for up to six hours may be employed to remove residual moisture prior to extrusion. Drying is not necessary for DOW ENDURANCE<sup>™</sup> HFDA-0801 BK EHV due to the lower moisture absorption characteristics relative to conventional semiconductive products.

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